100% Material Declaration Data Sheet TQG144

Average Weight: 1.4 g

Component	Substance Description	CAS# or Description	% of Component	Use in Product	Component Weight/ Substance Weight (in grams)	Component % of Total
Silicon Die					**0.0147**	**1.05%**
	Silicon	7440-21-3	100.00		0.0147	
Die Attach Material					**0.00224**	**0.16%**
	Silver	7440-22-4	78.00		0.0017472	
	Epoxy (EP)	Trade Secret	22.00		0.0004928	
Mold Compound					**1.10208**	**78.72%**
	Epoxy Resin (EP)	Trade Secret	9.00		0.0991872	
	Phenolic Resin	Trade Secret	7.00		0.0771456	
	Carbon Black	1333-86-4	0.50		0.0055104	
	Silica	60676-86-0	82.50		0.909216	
	Bismuth	7440-69-9	Max 1.00		0.0110208	
Leadframe					**0.26124**	**18.66%**
	Copper	7440-50-8	98.85		0.25823574	
	Chromium	7440-47-3	0.30		0.00078372	
	Tin	7440-31-5	0.25		0.0006531	
	Zinc	7440-66-6	0.60		0.00156744	
Leadframe Plating					**0.00112**	**0.08%**
	Silver	7440-22-4	100.00		0.00112	
Bond Wire					**0.00616**	**0.44%**
	Gold	7440-57-5	100.00		0.00616	
Ext. Plating					**0.01246**	**0.89%**
	Tin	7440-31-5	100.00		0.01246	

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Revision History

The following table shows the revision history for this document.

Date	Revision	Revision
2/09/06	1.0	Initial release.
7/10/06	1.1	100% Material Declaration.
9/28/06	1.2	Updated component descriptions.
10/19/06	1.2.1	Editorial change; corrected typo in Substance Description.

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